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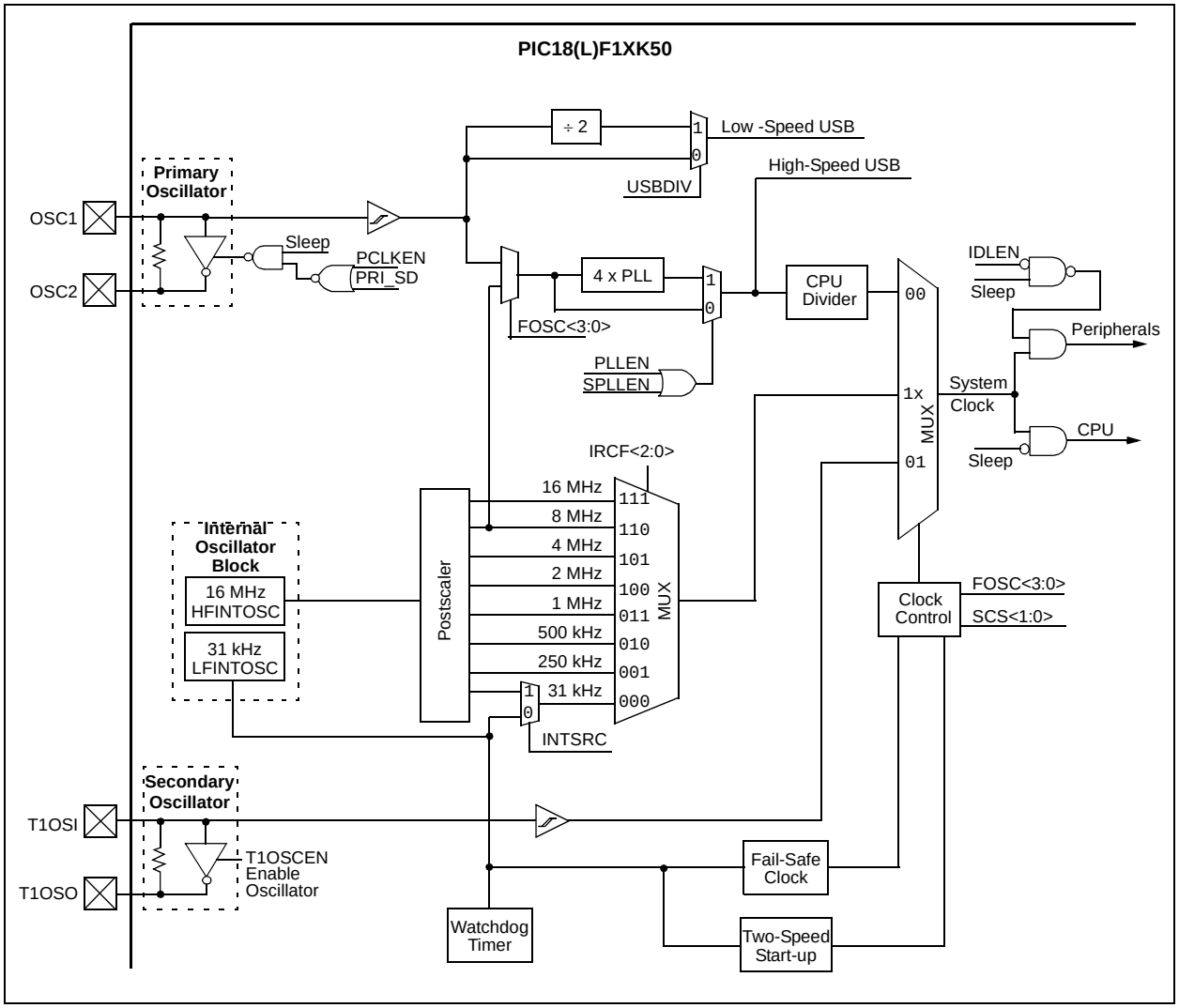
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	14
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f14k50-i-ss

FIGURE 2-1: PIC® MCU CLOCK SOURCE BLOCK DIAGRAM



REGISTER 7-9: IPR2: PERIPHERAL INTERRUPT PRIORITY REGISTER 2

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	U-0
OSCFIP	C1IP	C2IP	EEIP	BCLIP	USBIP	TMR3IP	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **OSCFIP:** Oscillator Fail Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **C1IP:** Comparator C1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **C2IP:** Comparator C2 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **EEIP:** Data EEPROM/Flash Write Operation Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **BCLIP:** Bus Collision Interrupt Priority bit
1 = High priority
0 = Low priority

bit 2 **USBIP:** USB Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR3IP:** TMR3 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **Unimplemented:** Read as ‘0’

REGISTER 9-16: ANSELH: ANALOG SELECT REGISTER 2

U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	—	ANS11	ANS10	ANS9	ANS8
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3 **ANS11:** RB5 Analog Select Control bit
1 = Digital input buffer of RB5 is disabled
0 = Digital input buffer of RB5 is enabled

bit 2 **ANS10:** RB4 Analog Select Control bit
1 = Digital input buffer of RB4 is disabled
0 = Digital input buffer of RB4 is enabled

bit 1 **ANS9:** RC7 Analog Select Control bit
1 = Digital input buffer of RC7 is disabled
0 = Digital input buffer of RC7 is enabled

bit 0 **ANS8:** RC6 Analog Select Control bit
1 = Digital input buffer of RC6 is disabled
0 = Digital input buffer of RC6 is enabled

9.5 Port Slew Rate Control

The output slew rate of each port is programmable to select either the standard transition rate or a reduced transition rate of 0.1 times the standard to minimize EMI. The reduced transition time is the default slew rate for all ports.

REGISTER 9-17: SLRCON: SLEW RATE CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	SLRC	SLRB	SLRA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **SLRC:** PORTC Slew Rate Control bit
1 = All outputs on PORTC slew at 0.1 times the standard rate
0 = All outputs on PORTC slew at the standard rate

bit 1 **SLRB:** PORTB Slew Rate Control bit
1 = All outputs on PORTB slew at 0.1 times the standard rate
0 = All outputs on PORTB slew at the standard rate

bit 0 **SLRA:** PORTA Slew Rate Control bit
1 = All outputs on PORTA slew at 0.1 times the standard rate(1)
0 = All outputs on PORTA slew at the standard rate

Note 1: The slew rate of RA4 defaults to standard rate when the pin is used as CLKOUT.

FIGURE 15-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

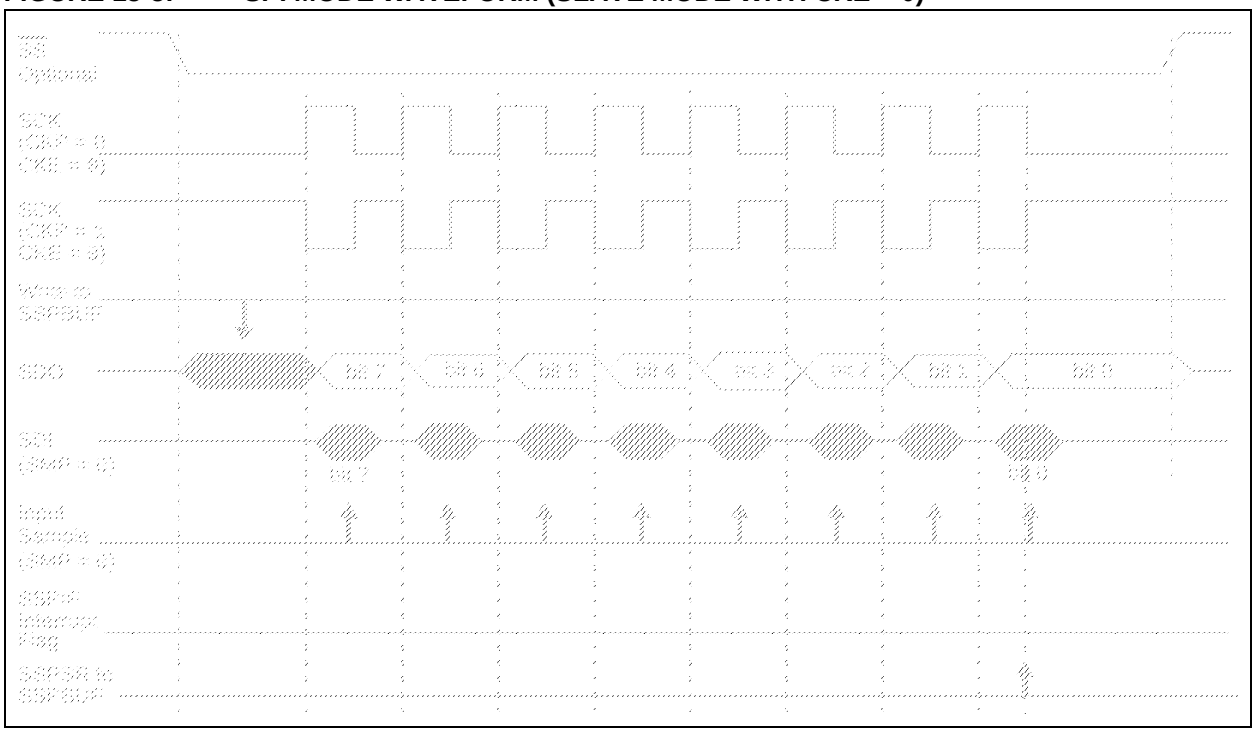
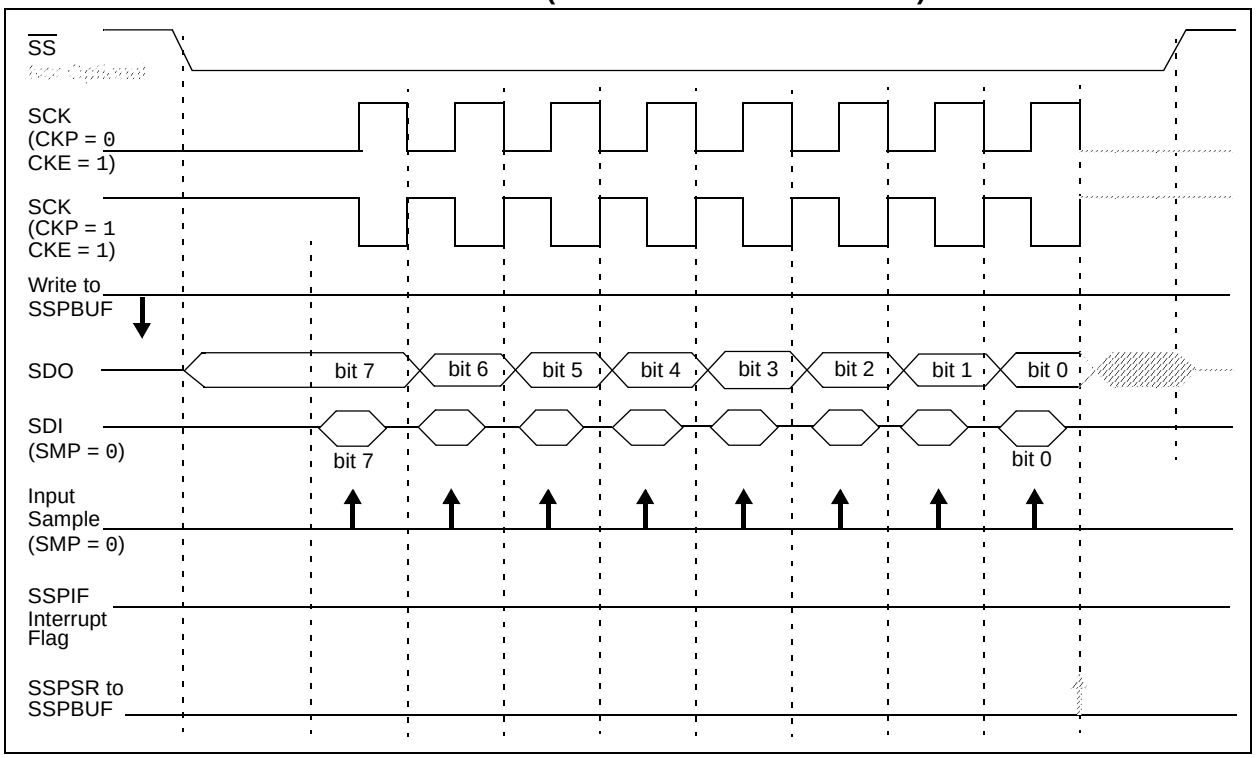


FIGURE 15-6: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



15.3.17.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the Start condition (Figure 15-26).

b) SCL is sampled low before SDA is asserted low (Figure 15-27).

During a Start condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

- the Start condition is aborted,
- the BCLIF flag is set and
- the MSSP module is reset to its Idle state (Figure 15-26).

The Start condition begins with the SDA and SCL pins deasserted. When the SDA pin is sampled high, the Baud Rate Generator is loaded and counts down. If the SCL pin is sampled low while SDA is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 15-28). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to 0; if the SCL pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 15-26: BUS COLLISION DURING START CONDITION (SDA ONLY)

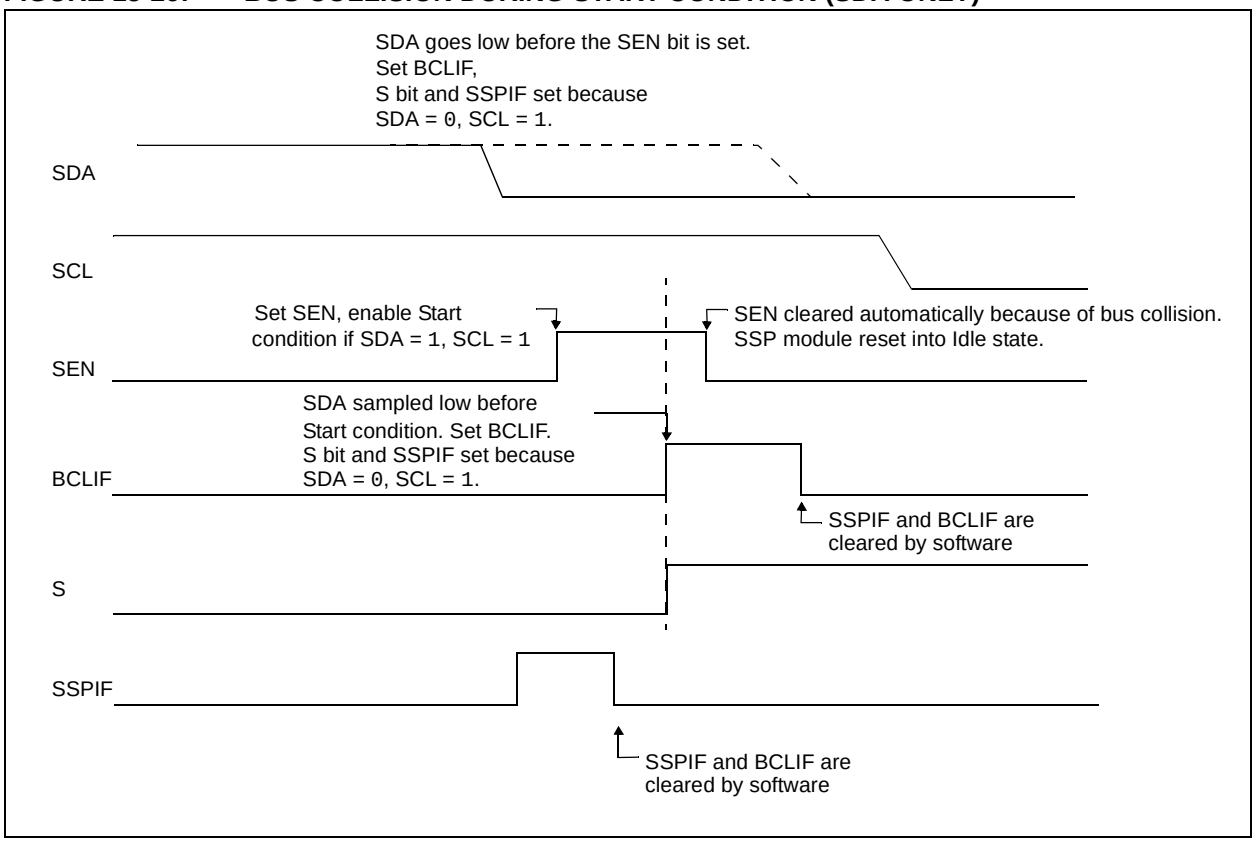


TABLE 16-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RABIE	TMR0IF	INT0IF	RABIF	275
PIR1	—	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	278
PIE1	—	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	278
IPR1	—	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	278
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	277
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	278
TXREG	EUSART Transmit Register								277
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	277
BAUDCON	ABDOVF	RCIDL	DTRXP	CKTXP	BRG16	—	WUE	ABDEN	277
SPBRGH	EUSART Baud Rate Generator Register, High Byte								277
SPBRG	EUSART Baud Rate Generator Register, Low Byte								277

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous master transmission.

16.4.1.6 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver must be disabled by setting the corresponding TRIS bits when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are un-read characters in the receive FIFO.

16.4.1.7 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver must be disabled by setting the associated TRIS bit when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

16.4.1.8 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

17.1.6 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital Conversion. The ADC interrupt flag is the ADIF bit in the PIR1 register. The ADC interrupt enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared by software.

Note:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the global interrupt must be disabled. If the global interrupt is enabled, execution will switch to the Interrupt Service Routine. Please see **Section 17.1.6 "Interrupts"** for more information.

TABLE 17-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (TAD)		Device Frequency (FOSC)			
ADC Clock Source	**ADCS<2:0>**	**48 MHz**	**16 MHz**	**4 MHz**	**1 MHz**
FOSC/2	000	41.67 ns(2)	125 ns(2)	500 ns(2)	2.0 μs
FOSC/4	100	83.33 ns(2)	250 ns(2)	1.0 μs	4.0 μs
FOSC/8	001	167 ns(2)	500 ns(2)	2.0 μs	8.0 μs(3)
FOSC/16	101	333 ns(2)	1.0 μs	4.0 μs	16.0 μs(3)
FOSC/32	010	667 ns(2)	2.0 μs	8.0 μs(3)	32.0 μs(3)
FOSC/64	110	1.33 μs	4.0 μs	16.0 μs(3)	64.0 μs(3)
FRC	x11	1-4 μs(1,4)	1-4 μs(1,4)	1-4 μs(1,4)	1-4 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The FRC source has a typical TAD time of 1.7 μs.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the FRC clock source is only recommended if the conversion will be performed during Sleep.

17.1.7 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON2 register controls the output format.

Figure 17-2 shows the two output formats.

FIGURE 17-2: 10-BIT A/D CONVERSION RESULT FORMAT

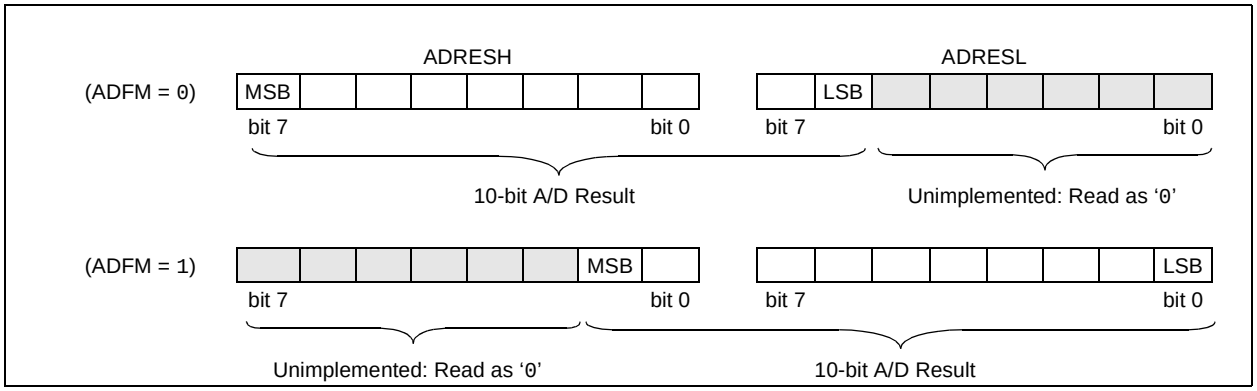
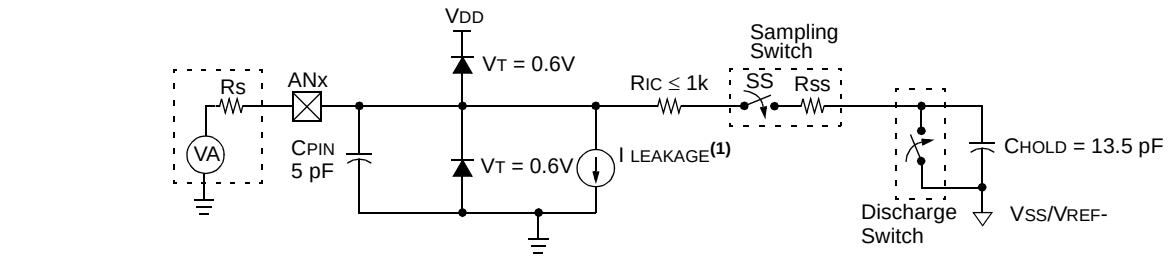
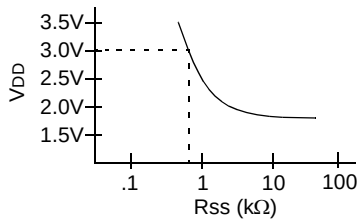


FIGURE 17-5: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
VT = Threshold Voltage
I LEAKAGE = Leakage current at the pin due to various junctions
RIC = Interconnect Resistance
SS = Sampling Switch
CHOLD = Sample/Hold Capacitance



Note 1: See **Section 27.0 "Electrical Specifications"**.

FIGURE 17-6: ADC TRANSFER FUNCTION

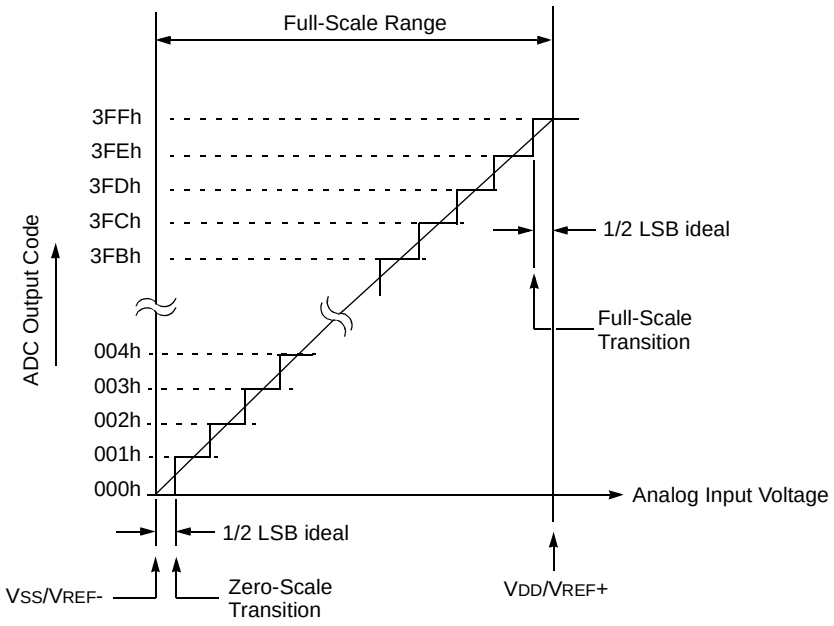
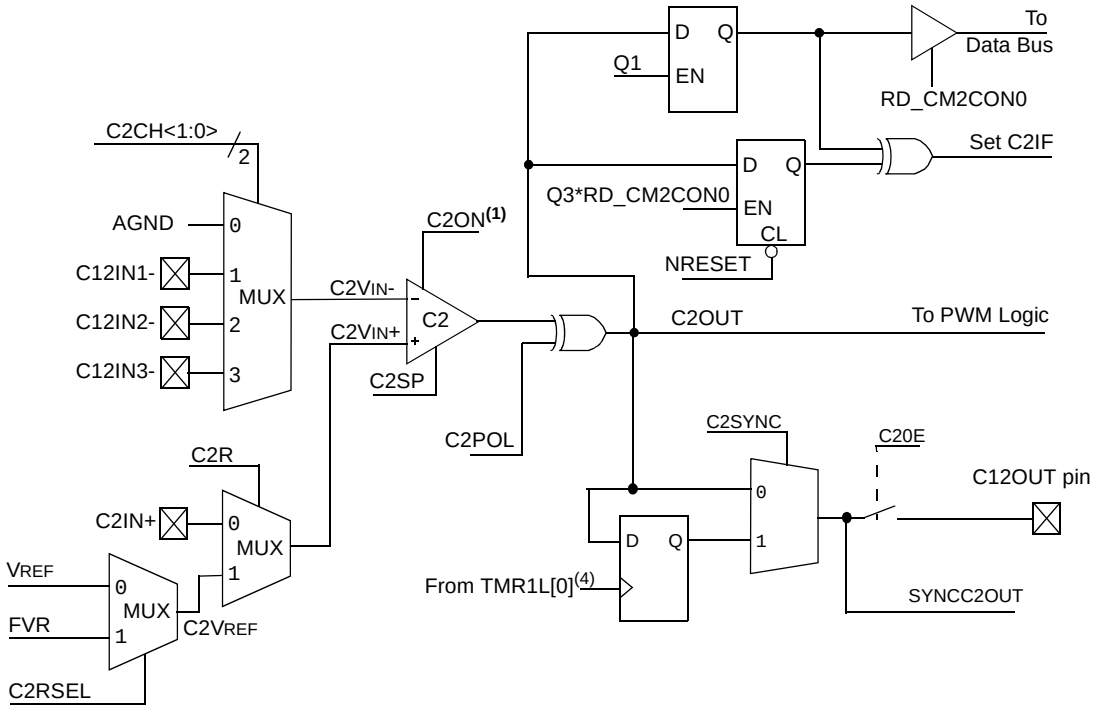


FIGURE 18-3: COMPARATOR C2 SIMPLIFIED BLOCK DIAGRAM



Note 1: When C2ON = 0, the C2 comparator will produce a '0' output to the XOR Gate.
2: Q1 and Q3 are phases of the four-phase system clock (FOSC).
3: Q1 is held high during Sleep mode.
4: Positive going pulse generated on both falling and rising edges of the bit.

18.4 Comparator Interrupt Operation

The comparator interrupt flag can be set whenever there is a change in the output value of the comparator. Changes are recognized by means of a mismatch circuit which consists of two latches and an exclusive-or gate (see Figure 18-2 and Figure 18-3). One latch is updated with the comparator output level when the CMxCON0 register is read. This latch retains the value until the next read of the CMxCON0 register or the occurrence of a Reset. The other latch of the mismatch circuit is updated on every Q1 system clock. A mismatch condition will occur when a comparator output change is clocked through the second latch on the Q1 clock cycle. At this point the two mismatch latches have opposite output levels which is detected by the exclusive-or gate and fed to the interrupt circuitry. The mismatch condition persists until either the CMxCON0 register is read or the comparator output returns to the previous state.

Note 1: A write operation to the CMxCON0 register will also clear the mismatch condition because all writes include a read operation at the beginning of the write cycle.

2: Comparator interrupts will operate correctly regardless of the state of CxOE.

The comparator interrupt is set by the mismatch edge and not the mismatch level. This means that the interrupt flag can be reset without the additional step of reading or writing the CMxCON0 register to clear the mismatch registers. When the mismatch registers are cleared, an interrupt will occur upon the comparator's return to the previous state, otherwise no interrupt will be generated.

Software will need to maintain information about the status of the comparator output, as read from the CMxCON0 register, or CM2CON1 register, to determine the actual change that has occurred. See Figures 18-4 and 18-5.

The CxIF bit of the PIR2 register is the comparator interrupt flag. This bit must be reset by software by clearing it to '0'. Since it is also possible to write a '1' to this register, an interrupt can be generated.

In mid-range Compatibility mode the CxIE bit of the PIE2 register and the PEIE and GIE bits of the INTCON register must all be set to enable comparator interrupts. If any of these bits are cleared, the interrupt is not enabled, although the CxIF bit of the PIR2 register will still be set if an interrupt condition occurs.

18.4.1 PRESETTING THE MISMATCH LATCHES

The comparator mismatch latches can be preset to the desired state before the comparators are enabled. When the comparator is off the CxPOL bit controls the CxOUT level. Set the CxPOL bit to the desired CxOUT non-interrupt level while the CxON bit is cleared. Then, configure the desired CxPOL level in the same instruction that the CxON bit is set. Since all register writes are performed as a Read-Modify-Write, the mismatch latches will be cleared during the instruction Read phase and the actual configuration of the CxON and CxPOL bits will be occur in the final Write phase.

FIGURE 18-4: COMPARATOR INTERRUPT TIMING WITHOUT CMxCON0 READ

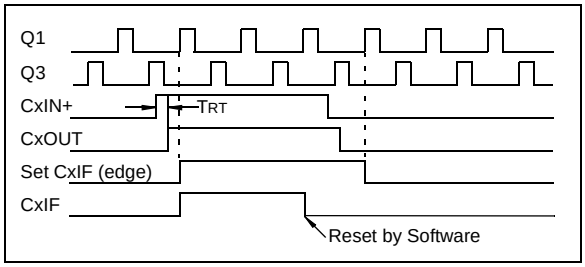
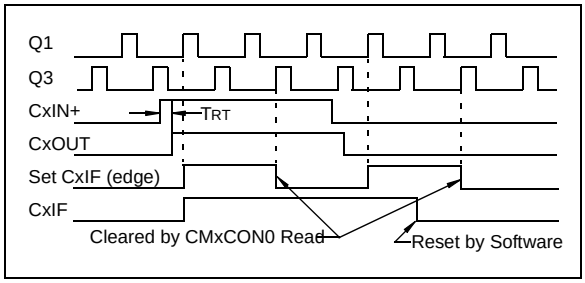


FIGURE 18-5: COMPARATOR INTERRUPT TIMING WITH CMxCON0 READ



Note 1: If a change in the CMxCON0 register (CxOUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CxIF interrupt flag of the PIR2 register may not get set.

2: When either comparator is first enabled, bias circuitry in the Comparator module may cause an invalid output from the comparator until the bias circuitry is stable. Allow about 1 μs for bias settling then clear the mismatch condition and interrupt flags before enabling comparator interrupts.

23.4 Brown-out Reset (BOR)

PIC18(L)F1XK50 devices implement a BOR circuit that provides the user with a number of configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> bits of the CONFIG2L Configuration register. There are a total of four BOR configurations which are summarized in Table 23-1.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '00'), any drop of V_{DD} below V_{BOR} for greater than T_{BOR} will reset the device. A Reset may or may not occur if V_{DD} falls below V_{BOR} for less than T_{BOR}. The chip will remain in Brown-out Reset until V_{DD} rises above V_{BOR}.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above V_{BOR}; it then will keep the chip in Reset for an additional time delay, T_{PWRT}. If V_{DD} drops below V_{BOR} while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once V_{DD} rises above V_{BOR}, the Power-up Timer will execute the additional time delay.

BOR and the Power-on Timer (PWRT) are independently configured. Enabling BOR Reset does not automatically enable the PWRT.

23.4.1 SOFTWARE ENABLED BOR

When BOREN<1:0> = 01, the BOR can be enabled or disabled by the user in software. This is done with the SBOREN control bit of the RCON register. Setting SBOREN enables the BOR to function as previously described. Clearing SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise it is read as '0'.

Placing the BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change BOR configuration. It also allows the user to tailor device power consumption in software by eliminating the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits. It cannot be changed by software.

23.4.2 DETECTING BOR

When BOR is enabled, the $\overline{BOR}$ bit always resets to '0' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of $\overline{BOR}$ alone. A more reliable method is to simultaneously check the state of both $\overline{POR}$ and $\overline{BOR}$. This assumes that the $\overline{POR}$ and $\overline{BOR}$ bits are reset to '1' by software immediately after any POR event. If $\overline{BOR}$ is '0' while $\overline{POR}$ is '1', it can be reliably assumed that a BOR event has occurred.

23.4.3 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, the BOR remains under hardware control and operates as previously described. Whenever the device enters Sleep mode, however, the BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code, when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

TABLE 23-1: BOR CONFIGURATIONS

BOR Configuration		Status of SBOREN (RCON<6>)	BOR Operation
BOREN1	BOREN0		
0	0	Unavailable	BOR disabled; must be enabled by reprogramming the Configuration bits.
0	1	Available	BOR enabled by software; operation controlled by SBOREN.
1	0	Unavailable	BOR enabled by hardware in Run and Idle modes, disabled during Sleep mode.
1	1	Unavailable	BOR enabled by hardware; must be disabled by reprogramming the Configuration bits.

FIGURE 23-3: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD, VDD RISE < TPWRT)

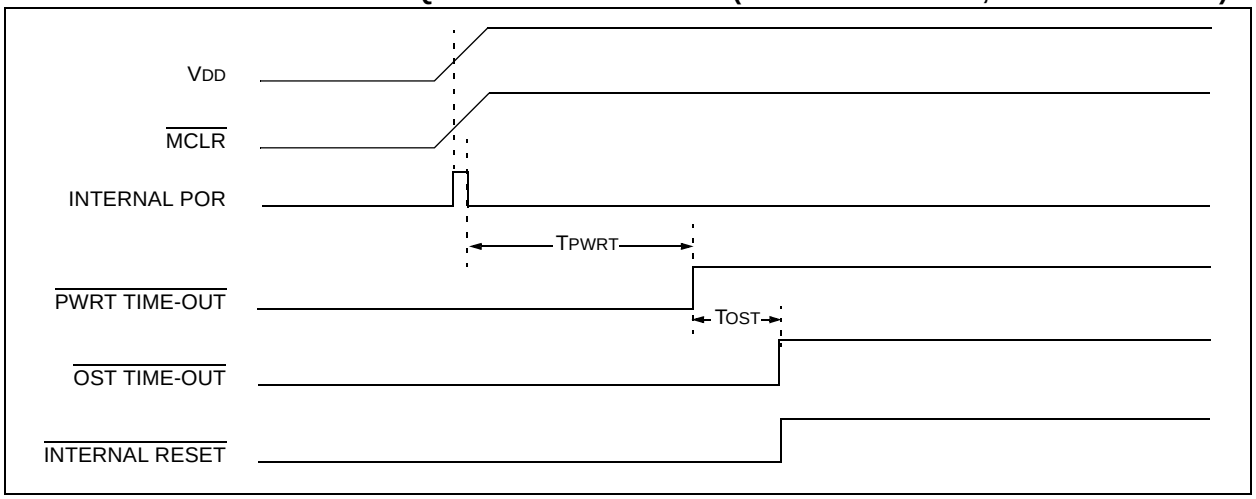


FIGURE 23-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

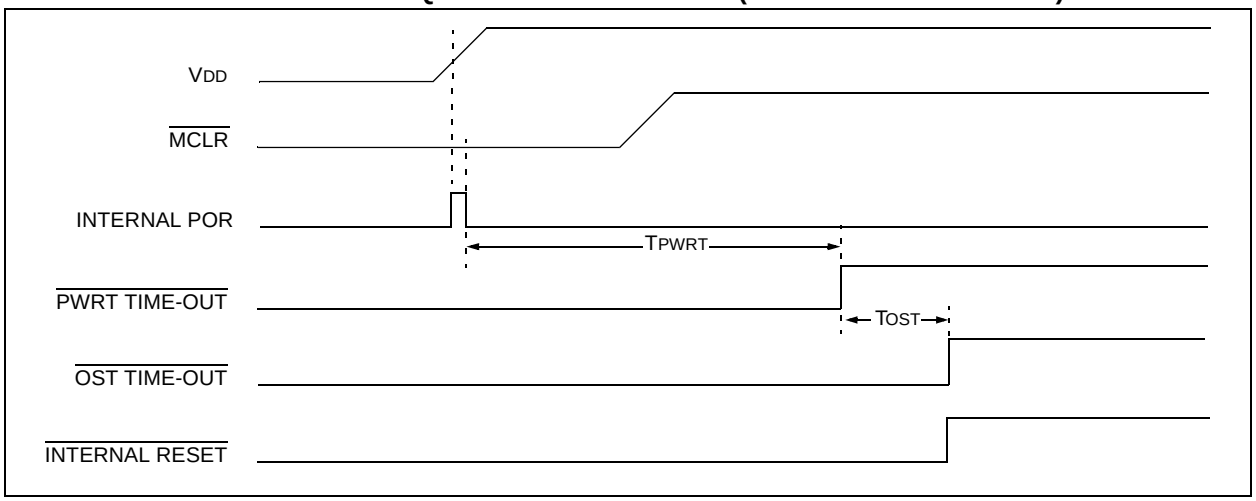
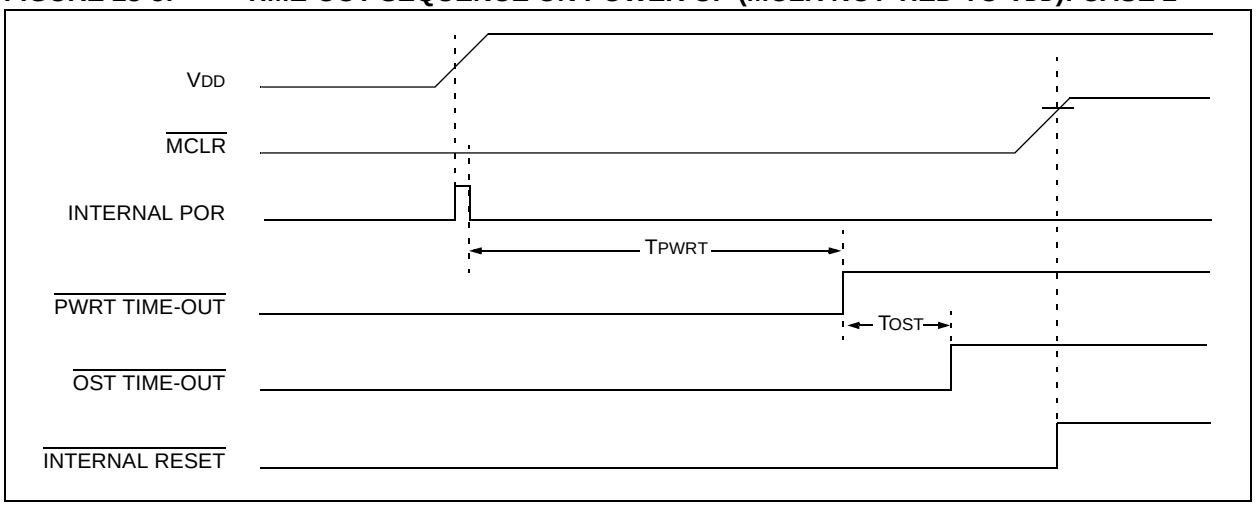


FIGURE 23-5: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2



25.0 INSTRUCTION SET SUMMARY

PIC18(L)F1XK50 devices incorporate the standard set of 75 PIC18 core instructions, as well as an extended set of 8 new instructions, for the optimization of code that is recursive or that utilizes a software stack. The extended set is discussed later in this section.

25.1 Standard Instruction Set

The standard PIC18 instruction set adds many enhancements to the previous PIC MCU instruction sets, while maintaining an easy migration from these PIC MCU instruction sets. Most instructions are a single program memory word (16 bits), but there are four instructions that require two program memory locations.

Each single-word instruction is a 16-bit word divided into an opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into four basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal** operations
- **Control** operations

The PIC18 instruction set summary in Table 25-2 lists **byte-oriented**, **bit-oriented**, **literal** and **control** operations. Table 25-1 shows the opcode field descriptions.

Most **byte-oriented** instructions have three operands:

1. The file register (specified by ‘f’)
2. The destination of the result (specified by ‘d’)
3. The accessed memory (specified by ‘a’)

The file register designator ‘f’ specifies which file register is to be used by the instruction. The destination designator ‘d’ specifies where the result of the operation is to be placed. If ‘d’ is zero, the result is placed in the WREG register. If ‘d’ is one, the result is placed in the file register specified in the instruction.

All **bit-oriented** instructions have three operands:

1. The file register (specified by ‘f’)
2. The bit in the file register (specified by ‘b’)
3. The accessed memory (specified by ‘a’)

The bit field designator ‘b’ selects the number of the bit affected by the operation, while the file register designator ‘f’ represents the number of the file in which the bit is located.

The **literal** instructions may use some of the following operands:

- A literal value to be loaded into a file register (specified by ‘k’)
- The desired FSR register to load the literal value into (specified by ‘f’)
- No operand required (specified by ‘—’)

The **control** instructions may use some of the following operands:

- A program memory address (specified by ‘n’)
- The mode of the CALL or RETURN instructions (specified by ‘s’)
- The mode of the table read and table write instructions (specified by ‘m’)
- No operand required (specified by ‘—’)

All instructions are a single word, except for four double-word instructions. These instructions were made double-word to contain the required information in 32 bits. In the second word, the 4 MSbs are ‘1’s. If this second word is executed as an instruction (by itself), it will execute as a NOP.

All single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of the instruction. In these cases, the execution takes two instruction cycles, with the additional instruction cycle(s) executed as a NOP.

The double-word instructions execute in two instruction cycles.

One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true, or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs. Two-word branch instructions (if true) would take 3 μs.

Figure 25-1 shows the general formats that the instructions can have. All examples use the convention ‘nnh’ to represent a hexadecimal number.

The Instruction Set Summary, shown in Table 25-2, lists the standard instructions recognized by the Microchip Assembler (MPASM™).

Section 25.1.1 “Standard Instruction Set” provides a description of each instruction.

RRNCF **Rotate Right f (No Carry)**

Syntax: RRNCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

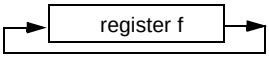
Operation: (f<n>) → dest<n – 1>,
(f<0>) → dest<7>

Status Affected: N, Z

Encoding:

0100	00da	ffff	ffff

Description: The contents of register ‘f’ are rotated one bit to the right. If ‘d’ is ‘0’, the result is placed in W. If ‘d’ is ‘1’, the result is placed back in register ‘f’ (default).
If ‘a’ is ‘0’, the Access Bank will be selected, overriding the BSR value. If ‘a’ is ‘1’, then the bank will be selected as per the BSR value (default).
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example 1: RRNCF REG, 1, 0

Before Instruction
REG = 1101 0111
After Instruction
REG = 1110 1011

Example 2: RRNCF REG, 0, 0

Before Instruction
W = ?
REG = 1101 0111
After Instruction
W = 1110 1011
REG = 1101 0111

SETF **Set f**

Syntax: SETF f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: FFh → f

Status Affected: None

Encoding:

0110	100a	ffff	ffff

Description: The contents of the specified register are set to FFh.
If ‘a’ is ‘0’, the Access Bank is selected.
If ‘a’ is ‘1’, the BSR is used to select the GPR bank (default).
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write register ‘f’

Example: SETF REG, 1

Before Instruction
REG = 5Ah
After Instruction
REG = FFh

TABLE 27-3: POWER-DOWN CURRENT, PIC18(L)F1XK50-I/E

PIC18LF1XK50			Standard Operating Conditions (unless otherwise stated)					
PIC18F1XK50			Standard Operating Conditions (unless otherwise stated)					
Param. No.	Device Characteristics	Min.	Typ.†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
	Power-down Base Current (I_{PD})(2)							
D027		—	0.024	1.0	7.0	µA	1.8	WDT, BOR, FVR, Voltage Regulator and T1OSC disabled, all Peripherals Inactive
		—	0.078	2.0	9.0	µA	3.0	
D027		—	3.5	9	13	µA	1.8	WDT, BOR, FVR and T1OSC disabled, all Peripherals Inactive
		—	4.0	13	16	µA	3.0	
		—	5.0	18	21	µA	5.0	
	Power-down Module Current							
D028		—	0.5	4.0	8.0	µA	1.8	LPWDT Current(1)
		—	0.8	5.0	10.0	µA	3.0	
D028		—	7	11	15	µA	1.8	LPWDT Current(1)
		—	10	15	18	µA	3.0	
		—	11	20	23	µA	5.0	
D029		—	12	20	25	µA	1.8	FVR current (3)
		—	20	30	35	µA	3.0	
D029		—	28	42	50	µA	1.8	FVR current(3, 5)
		—	36	46	55	µA	3.0	
		—	39	49	60	µA	5.0	
D030		—	6	15	20	µA	3.0	BOR Current(1, 3)
D030		—	12	35	40	µA	3.0	BOR Current(1, 3, 5)
		—	14	40	45	µA	5.0	
D031		—	0.79	4.0	6.0	µA	1.8	T1OSC Current(1)
		—	1.8	5.0	7.0	µA	3.0	
D031		—	3.5	10	14	µA	1.8	T1OSC Current(1)
		—	4.0	14	17	µA	3.0	
		—	5.0	19	22	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{DD} or I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD}.

3: Fixed Voltage Reference is automatically enabled whenever the BOR is enabled

4: A/D oscillator source is FRC

5: 330 µf capacitor on VUSB pin.

TABLE 27-4: INPUT/OUTPUT CHARACTERISTICS, PIC18(L)F1XK50-I/E

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param. No.	Sym.	Characteristic	Min.	Typ.†	Max.	Units	Conditions
	VIL	**Input Low Voltage**					
		I/O ports:					
D036		with TTL buffer	VSS	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D036A			VSS	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
D036B			VSS	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
D037		with Schmitt Trigger buffer	VSS	—	0.2 VDD	V	1.8V ≤ VDD ≤ 5.5V
D037A		with I^2C™ levels	VSS	—	0.3 VDD	V	
D037B		with SMBus levels	VSS	—	0.8 VDD	V	2.7V ≤ VDD ≤ 5.5V
D038		$\overline{MCLR}$	VSS	—	0.2 VDD	V	
D039		OSC1	VSS	—	0.3 VDD	V	HS, HSPLL modes
D039A		OSC1	VSS	—	0.2 VDD	V	EC, RC modes(1)
D039B		OSC1	VSS	—	0.3 VDD	V	XT, LP modes
D039C		T1CKI	VSS	—	0.3 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:					
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	VDD	V	1.8V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8 VDD	—	VDD	V	1.8V ≤ VDD ≤ 5.5V
D041A		with I^2C levels	0.7 VDD	—	VDD	V	
D037A		with SMBus levels	2.1	—	VDD	V	2.7V ≤ VDD ≤ 5.5V
D042		$\overline{MCLR}$	0.8 VDD	—	VDD	V	
D042A		$\overline{MCLR}$	0.9 VDD	—	0.3 VDD	V	1.8V ≤ VDD ≤ 2.4V
D043		OSC1	0.7 VDD	—	VDD	V	HS, HSPLL modes
D043A		OSC1	0.8 VDD	—	VDD	V	EC mode
D043B		OSC1	0.9 VDD	—	VDD	V	RC mode(1)
D043C		OSC1	1.6	—	VDD	V	XT, LP modes
D043E		T1CKI	1.6	—	VDD	V	
	IIL	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 100	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C to 85°C
			—	± 5	± 1000	nA	VSS ≤ VPIN ≤ VDD, 85°C to 125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD
	IPUR	**PORTB Weak Pull-up Current**					
D070*			50	250	400	µA	VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage(4)**					
D080		I/O ports	—	—	VSS+0.6 VSS+0.6 VSS+0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 3 mA, VDD = VDDMIN

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: Including OSC2 in CLKOUT mode.

27.4 AC Characteristics

Timing Parameter Symbology has been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

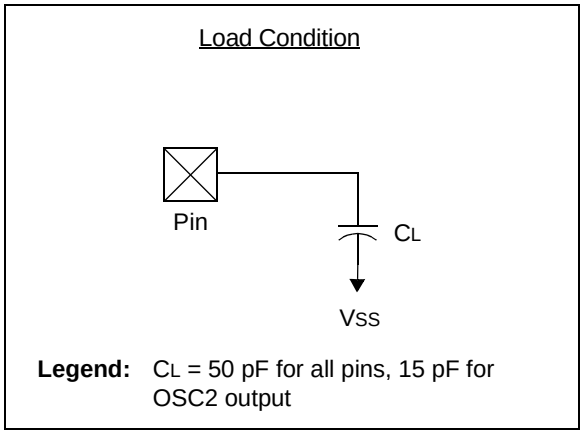
Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O PORT	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 27-2: LOAD CONDITIONS



Legend: CL = 50 pF for all pins, 15 pF for OSC2 output

Unless otherwise noted, V_{IN} = 5V, F_{OSC} = 300 kHz, C_{IN} = 0.1 µF, T_A = 25°C.

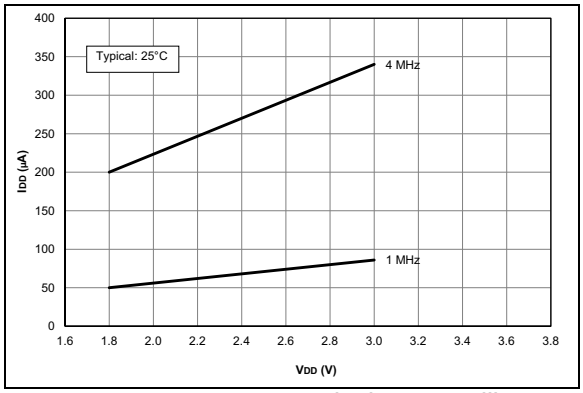


FIGURE 28-7: *IDD Typical, EC Oscillator, Medium-Power Mode, PIC18LF1XK50 Only.*

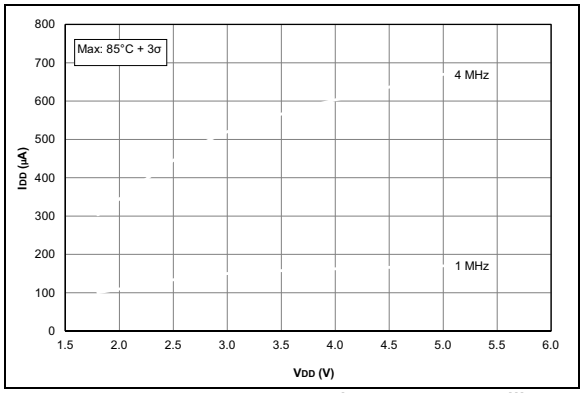


FIGURE 28-10: *IDD Maximum, EC Oscillator, Medium-Power Mode, PIC18F1XK50 Only.*

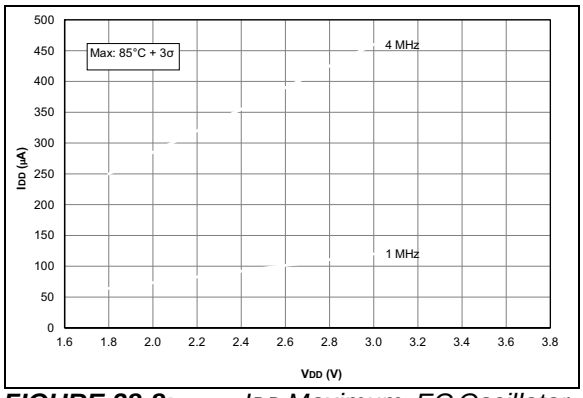


FIGURE 28-8: *IDD Maximum, EC Oscillator, Medium-Power Mode, PIC18LF1XK50 Only.*

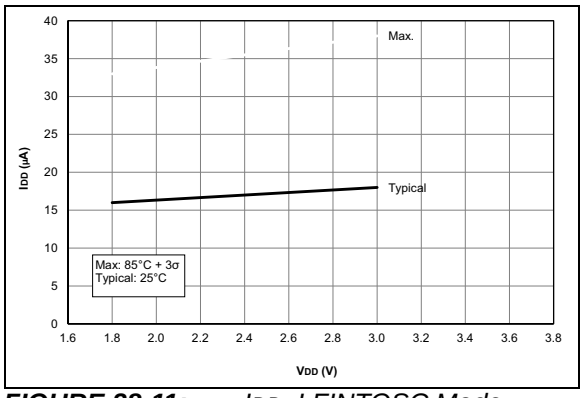


FIGURE 28-11: *IDD, LFINTOSC Mode, FOSC = 31 kHz, PIC18LF1XK50 Only.*

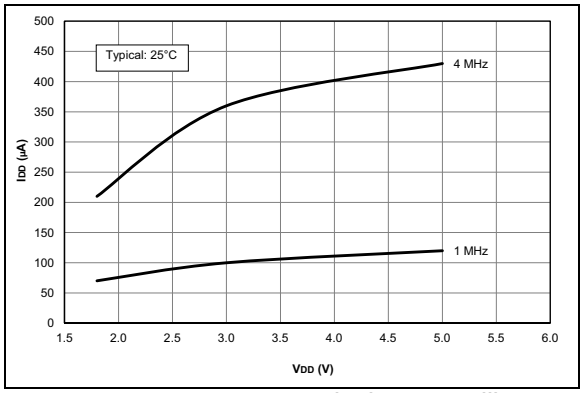


FIGURE 28-9: *IDD Typical, EC Oscillator, Medium-Power Mode, PIC18F1XK50 Only.*

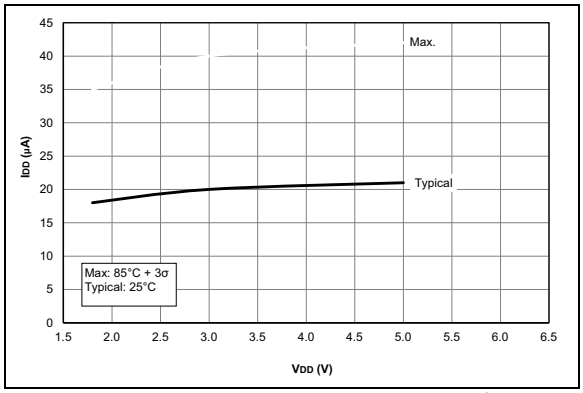
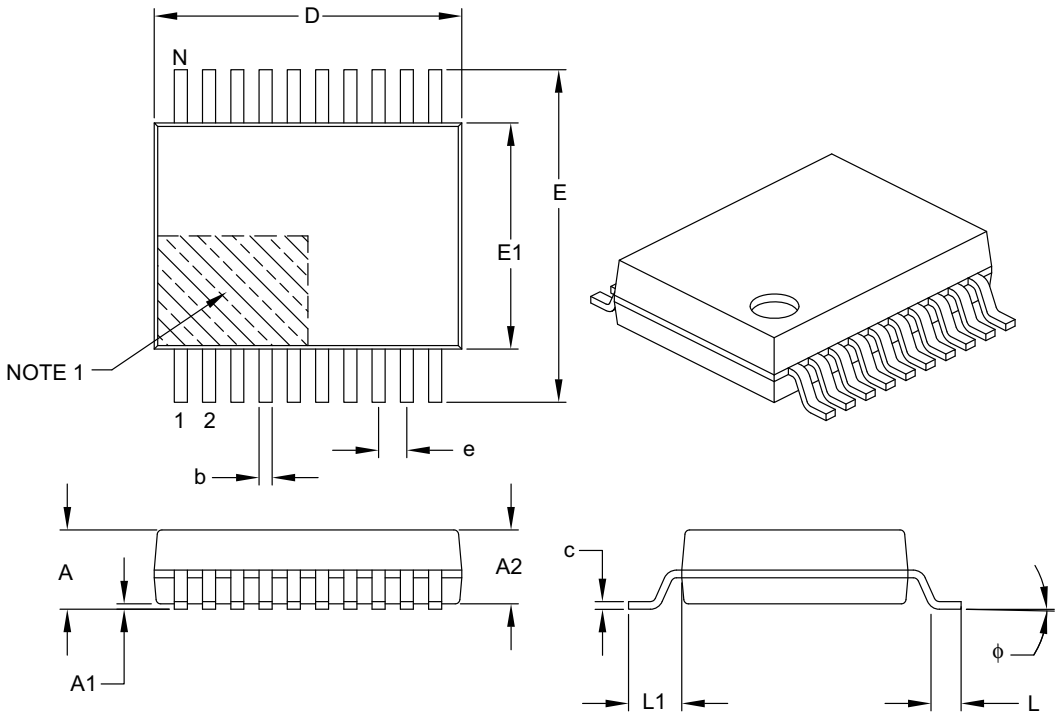


FIGURE 28-12: *IDD, LFINTOSC Mode, FOSC = 31 kHz, PIC18F1XK50 Only.*

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B